40V SILICON HIGH CURRENT LOW LEAKAGE SCHOTTKY DIODE

SUMMARY

Schottky Diode V_R = 40V; I_F = 2.2A; I_R = 40 μ A

DESCRIPTION

This compact SOT23-6 packaged Schottky diode offers users an excellent performance combination comprising high current operation, extremely low leakage and low forward voltage ensuring suitability for applications requiring efficient operation at higher temperatures (above 85°C) see Operational Efficiency chart on page 4.



Cathode

Key benefits:

Performance capability equivalent to much larger packages

Improved circuit efficiency & power levels

PCB area savings

FEATURES

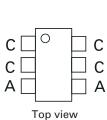
- · Low equivalent on resistance
- Extremely low leakage (40μA @30V)
- High current capability (I_F = 2.2A)
- Low V_F, fast switching Schottky
- SOT23-6 package
- ZLLS2000 complements low temperature equivalent ZHCS2000
- Package thermally rated to 150°C

APPLICATIONS

- DC DC converters
- Strobes
- Mobile phones
- Charging circuits
- Motor control

ORDERING INFORMATION

DEVICE	REEL (inches)		QUANTITY PER REEL
ZLLS2000TA	7	8mm embossed	3000 units
ZLLS2000TC	13	8mm embossed	10000 units



Anode

DEVICE MARKING

LL20



ABSOLUTE MAXIMUM RATINGS

PARAMETER		SYMBOL	VALUE	UNIT		
Schottky Diode						
Continuous reverse voltage		V _R	40	V		
Forward current		I _F	2.2	А		
Peak repetitive forward current		I _{FPK}	3.55	А		
Rectangular pulse duty cycle						
Non repetitive forward current	t=≤100μs	I _{FSM}	36	А		
	t=≤10ms		12	A		
Package						
Power dissipation at T _{amb} =25°C						
single die continuous		P_{D}	1.1	W		
single die measured at t<5 secs			1.71	W		
Storage temperature range		T _{stg}	-55 to +150	°C		
Junction temperature		тј	150	°C		

THERMAL RESISTANCE

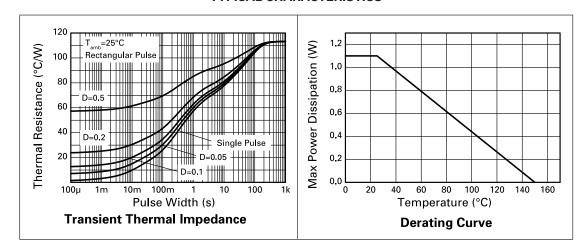
PARAMETER	SYMBOL	VALUE	UNIT
Junction to ambient (a)	$R_{\Theta JA}$	113	°C/W
Junction to ambient (b)	$R_{\Theta JA}$	73	°C/W

Notes

- (a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
- (b) For a device surface mounted on FR4 PCB measured at t<5secs.



TYPICAL CHARACTERISTICS





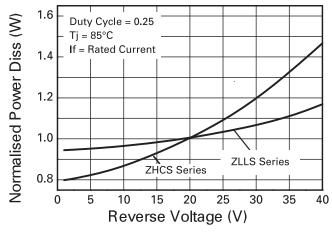
ELECTRICAL CHARACTERISTICS (at T_{amb} = 25°C unless otherwise stated)

SCHOTTKY DIODE CHARACTERISTICS						
						PARAMETER
Reverse breakdown voltage	$V_{(BR)R}$	40			V	I _R =1mA
Forward voltage	V _F		260	-	mV	I _F =50 mA*
			290	-	mV	I _F =100 mA*
			322	-	mV	I _F =250mA*
			345	370	mV	I _F =500mA*
			395	430	mV	I _F =1000mA*
			440	490	mV	I _F =1500mA*
			475	540	mV	I _F =2000mA*
			550	640	mV	I _F =3000mA*
			465			I _F =2000mA*,Ta = 100°C
Reverse current	I _R		25	40	μΑ	V _R =30V
			1.7		mA	V _R =30V, Ta=85°C
Diode capacitance	C _D		65		pF	f=1MHz,V _R =30V
Reverse recovery time	t _{rr}		6		ns	Switched from
Reverse recovery charge	Q _{rr}		685		pC	I_F = 500mA to V_R = 5.5V Measured @ I_R 50mA. di / dt > 500mA / ns. Rsource = 6 Ω ; Rload= 10 Ω

^{*}Measured under pulsed conditions. Pulse width=300µs. Duty cycle $\leq 2\%$

Operational efficiency chart

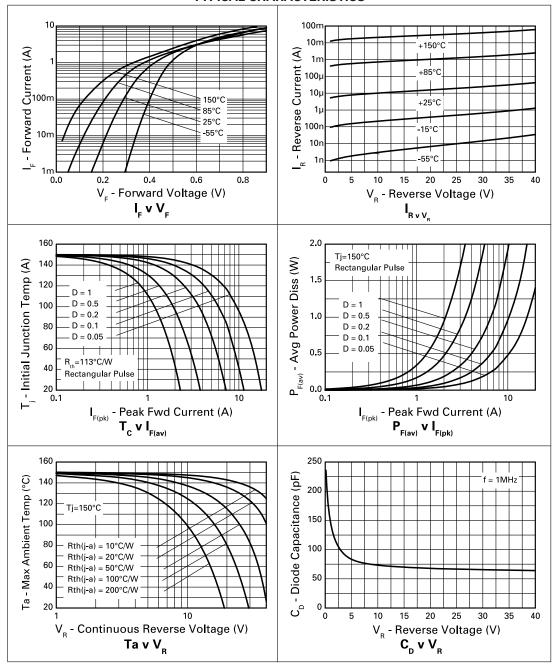
The operational efficiency chart indicates the beneficial use of the ZLLS series diodes in applications requiring higher voltage, higher temperature operation. Circuits requiring low voltage low temperature operation will benefit from using Zetex low V_F ZHCS series diodes.



Operational Efficiency Example



TYPICAL CHARACTERISTICS



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- "Not recommended for new designs"Device is still in production to support existing designs and production
- "Obsolete"Production has been discontinued

Datasheet status key:

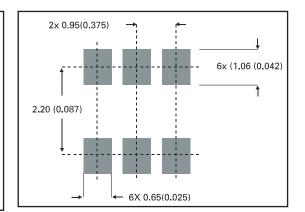
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PACKAGE DIMENSIONS

D C/L COMPLY TO TIA SC 74

PAD LAYOUT DETAILS



DIM	Millimeters				
	Min.	Max.			
Α	0.90	1.45			
A1	0.00	0.15			
A2	0.90	1.30			
b	0.20	0.50			
С	0.09	0.26			
D	2.70	3.10			
Е	2.20	3.20			
E1	1.30	1.80			
L	0.10	0.60			
е	0.95 REF				
e1	1.90 REF				
θ	0°	30°			

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